



**Features**

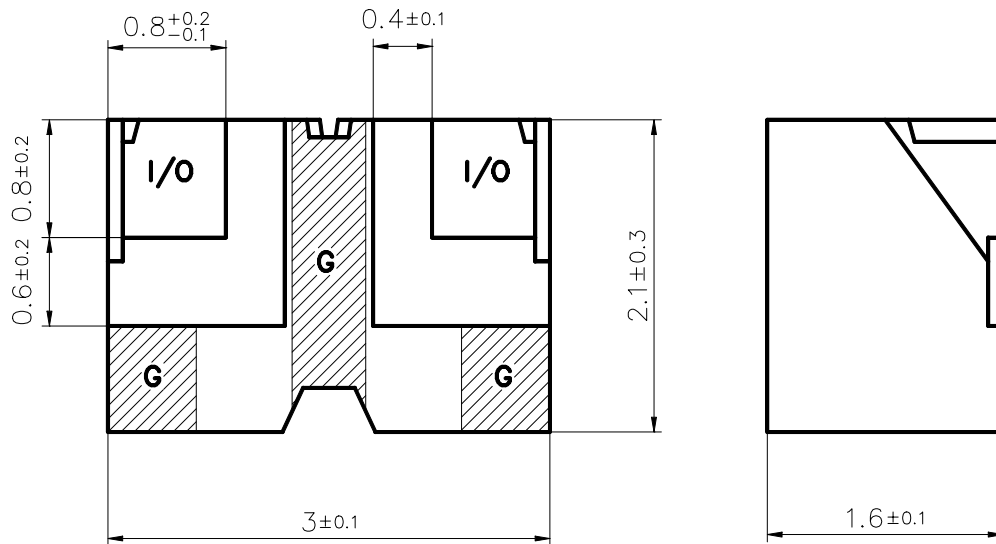
- SMD filter consisting of coupled resonators with stepped impedances
- MgTiO<sub>3</sub> - CaTiO<sub>3</sub> ( $\epsilon_r = 21$  /  $TC_f = 0 \pm 10$  ppm/K) with a coating of copper (10 $\mu$ m) and tin (>5 $\mu$ m)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

**Index**

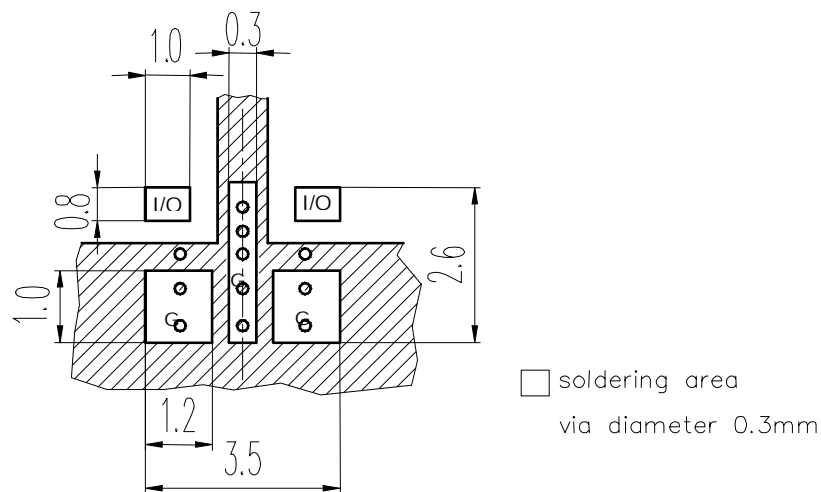
- Page 2
  - Component drawing
  - Recommended footprint
- Page 3
  - Characteristics
  - Maximum ratings
  - Typical passband characteristic
- Page 4
  - Processing information
  - Soldering requirements
  - Delivery mode

ISSUE DATE	18.09.03	ISSUE	P2	PUBLISHER	SAW MWC PD F	PAGE	1/4
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Component drawing



Recommended footprint



ISSUE DATE	18.09.03	ISSUE	P2	PUBLISHER	SAW MWC PD F	PAGE	2/4
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Preliminary Datasheet

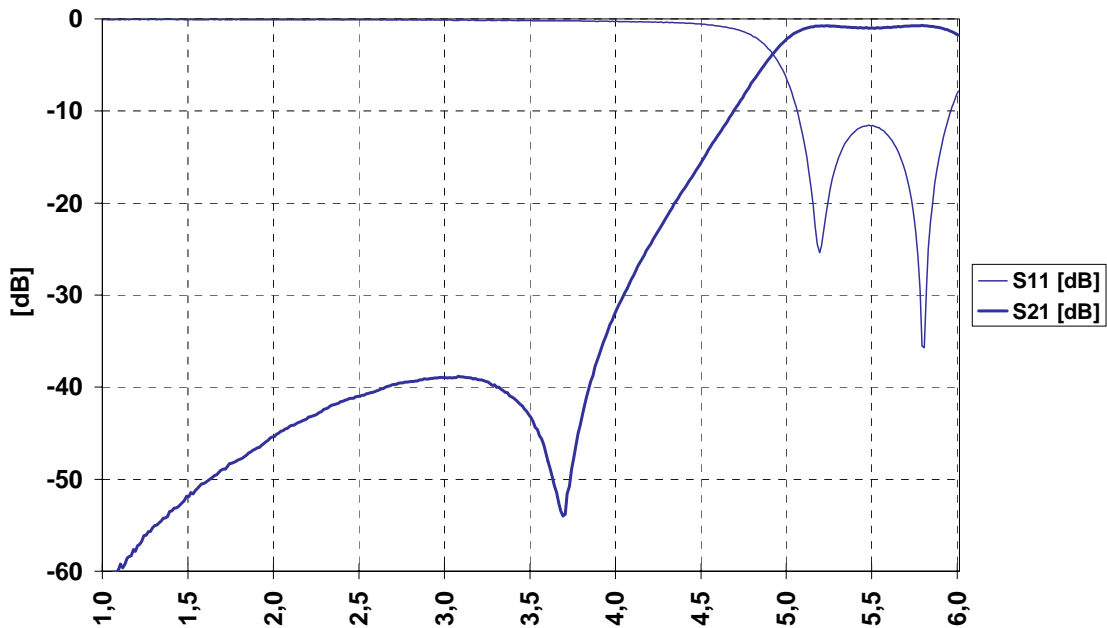
Characteristics

		min.	typ.	max.	
Center frequency	$f_c$			5.5	GHz
Insertion loss [5150 – 5850] MHz	$\alpha_{IL}$		1.0	1.4	dB
Passband [5150 – 5850] MHz	$B$	700			MHz
Amplitude ripple (peak - peak) [5150 – 5850] MHz	$\Delta\alpha$				dB
Standing wave ratio [5150 – 5850] MHz	$SWR$		1.8	2.0	
Impedance	$Z$		50		$\Omega$
Power	$P$			1.0	W
Attenuation	$\alpha$	at DC to 1990 MHz	45	50	dB
		at 1990 to 2170 MHz	42	45	dB
		at 2400 to 2500 MHz	40	43	dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	$T_{op}$	-40 / +85	°C

Typical passband characteristic



**Processing information**

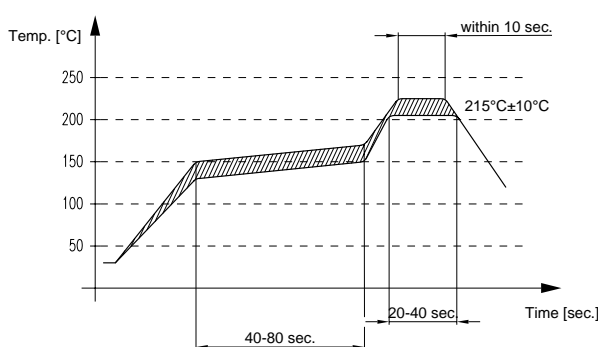
ZNr.: 577 (FILT95\_2)

- Wettability to IEC 68-2-58:  $\geq 75\%$  (after aging)

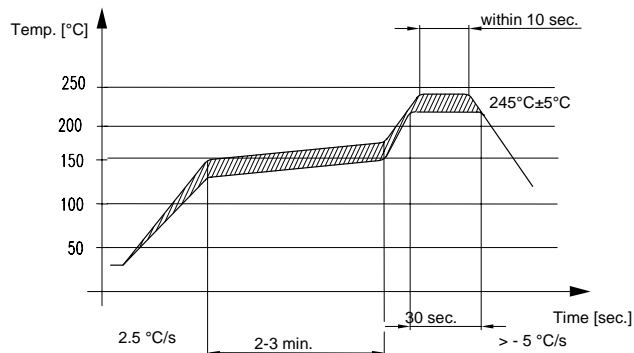
**Soldering requirements**

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):



eutectic SnPb solder paste profile



leadfree solder paste profile

**Delivery mode**

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: t.b.d.

t.b.d.

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ISSUE DATE	18.09.03	ISSUE	P2	PUBLISHER	SAW MWC PD F	PAGE	4/4
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